

Description

Aceso® PEM 2420 is a low density polyethylene made by a high pressure autoclave process without antioxidant. This grade is particularly suitable for the blown film, injection blow molding and extrusion blow molding processes.

Aceso® PEM 2420 has been specifically designed for the manufacture of healthcare products and pharmaceutical packaging like bags, pouches, blow-fill-seal applications, medical films, tubes, etc... However it is recommended to contact your local sales representative to obtain specific information and individual certificates regarding compliance to regulations.

Characteristics

Property	Method	Unit	Typical value
Density	ISO 1183	g/cm ³	0.923
Melt Flow Rate (190°C/2.16 kg)	ISO 1133	g/10 min	2.3
Melting temperature	ISO 11357	°C	109
Vicat temperature	ISO 306	°C	96

Values indicated are typical for this product. Density and MFR are properties routinely measured during "the standard quality control procedure". The other figures are generated by tests not included in the "standard quality control procedure", and are given for information only. Data are not intended for specification purposes.

Processing

Advised temperature profile: 160 to 200°C.

Handling and storage

Please refer to the safety data sheet (SDS) for handling and storage information. It is advisable to convert the product within one year after delivery provided storage conditions are used as given in the SDS of our product. SDS may be obtained from the website:

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